



Material Content Data Sheet



Sales Product Name		SAK-XC167CI-32F40F BB-A		Issued		24. January 2018		
MA#		MA001322924						
Package		PG-TQFP-144-7		Weight*		1403.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	33.010	2.35	2.35	23517	23517
leadframe	non noble metal	magnesium	7439-95-4	0.529	0.04		377	
	inorganic material	silicon	7440-21-3	2.293	0.16		1633	
	non noble metal	nickel	7440-02-0	10.581	0.75		7539	
	non noble metal	copper	7440-50-8	339.310	24.17	25.12	241735	251284
wire	noble metal	gold	7440-57-5	3.622	0.26	0.26	2580	2580
encapsulation	organic material	carbon black	1333-86-4	4.974	0.35		3543	
	plastics	epoxy resin	-	134.293	9.57		95674	
	inorganic material	silicondioxide	60676-86-0	855.493	60.95	70.87	609478	708695
leadfinish	non noble metal	tin	7440-31-5	8.638	0.62	0.62	6154	6154
plating	noble metal	silver	7440-22-4	4.833	0.34	0.34	3443	3443
glue	plastics	epoxy resin	-	1.215	0.09		865	
	noble metal	silver	7440-22-4	4.859	0.35	0.44	3462	4327
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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